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Contents

vii *Authors*
ix *Conference Committee*

NEW TECHNOLOGIES IN DLW: JOINT SESSION WITH 10909 AND 10930

10909 03 **Axial resolution improvement in multiphoton polymerization by 4Pi excitation** [10909-2]

POWDER-BED SLM METAL PRINTING

10909 07 **A deep dive into metal 3D printing (Invited Paper)** [10909-6]

10909 08 **Influence of multi-spot exposure of powder bed on melt pool stability in selective laser melting** [10909-7]

10909 09 **Area melting with multi-laser arrays to increase build rate for metal powder bed fusion additive manufacturing** [10909-8]

10909 0A **Concepts for integrating laser polishing into an additive manufacturing system** [10909-9]

NEW TECHNOLOGY FOR COPPER PRINTING

10909 0C **Blues skies for copper cladding with 450nm (Invited Paper)** [10909-11]

10909 0D **Additive manufacturing of pure copper using ultrashort laser pulses** [10909-12]

MULTI-MATERIALS PRINTING

10909 0G **Individual material and process development in laser based additive manufacturing** [10909-15]

10909 0H **Phenomena in multi-material fabrication using laser metal deposition (Invited Paper)** [10909-16]

LASER CLADDING AND HOT WIRE PRINTING

- 10909 OJ **Wire-based direct metal deposition with Ti6Al4V (Invited Paper)** [10909-17]
- 10909 OL **Additive manufacturing by wire based laser metal deposition (Invited Paper)** [10909-19]

PROCESS MONITORING AND CONTROL

- 10909 OM **Influence of energy input on spatter generation of 316L stainless steel fabrication by SLM in vacuum (Invited Paper)** [10909-20]
- 10909 OO **Layer-wise powder deposition defect detection in additive manufacturing** [10909-22]

NOVEL MATERIAL AND DEVICE PRINTING

- 10909 OP **Inkjet printing enabled rapid prototyping and model verification processes (Invited Paper)** [10909-24]
- 10909 OQ **Direct write of photonics using a filament-fed laser-heated process** [10909-25]

MICROPRINTING AND FORWARD TRANSFER

- 10909 OT **Femtosecond laser induced damage threshold (LIDT) of 3D nanolithography made micro- and nano-optical elements** [10909-28]

3D METROLOGY AND INSPECTION

- 10909 OV **Time-based offline track planning of robot guided laser applications for complex 3D freeform surfaces (Invited Paper)** [10909-30]
- 10909 OW **Irradiation angle dependence and polarization dependence in 3D geometry measurement using AMCW LiDAR** [10909-31]

POSTER SESSION

- 10909 0Y **Pure copper layer formation on copper based alloy substrate with 100 W class blue diode laser**
[10909-33]
- 10909 0Z **Effect of input energy on densification for pure copper fabricated by SLM with blue diode laser**
[10909-34]
- 10909 16 **Precise and large-dynamic-range surface profilometry using time-of-flight detection of femtosecond optical pulses** [10909-41]

Authors

Numbers in the index correspond to the last two digits of the seven-digit citation identifier (CID) article numbering system used in Proceedings of SPIE. The first five digits reflect the volume number. Base 36 numbering is employed for the last two digits and indicates the order of articles within the volume. Numbers start with 00, 01, 02, 03, 04, 05, 06, 07, 08, 09, 0A, 0B...0Z, followed by 10-1Z, 20-2Z, etc.

Abe, N., 0Y
Arnaud, C., 0L
Bernthaler, T., 0G
Bogdan, David, 09
Börret, R., 0V
Braun, M., 0V
Bristow, Douglas, 0Q
Britten, Simon W., 0C
Brow, Richard, 0Q
Brueckner, Frank, 0H
Butkutė, Agnė, 0T
Capps, Nicholas, 0Q
Carter, William, 09
Chen, Ray T., 0P
Davis, Thomas, 07
Ding, Yaoyu, 0J
Funada, Y., 0Y
Gadonas, Roldas, 03
Gailevičius, Darius, 0T
Goldstein, Jonathan, 0Q
Graham, Michael, 09
Grubb, Peter Mack, 0P
Hata, T., 0Y
Hayashi, Neisei, 0W
Hendriks, Adriaan, 0O
Higasino, R., 0Y
Hofele, M., 0G, 0V
Hori, Eiji, 0M
Hsu, Jen Hsien, 0Q
Huang, Jie, 0Q
Ilin, A., 08
Jeon, Chan-Gi, 16
Johnson, Jason E., 0Q
Jonušauskas, Linas, 0T
Kaden, Lisa, 0D
Karp, Jason, 09
Kiedrowski, T., 08
Kim, Jungwon, 16
Kinzel, Edward, 0Q
Kling, R., 0L
Kolb, D., 0G
Lachmayer, Roland, 0A
Landers, Robert, 0Q
Leuteritz, Georg, 0A
Leyens, Christoph, 0H
Liu, Shuang, 0J
López, Elena, 0H
Lu, Xing, 16
Malinauskas, Mangirdas, 0T
Marquardt, Franz, 0H
Masuno, S., 0Z
Matthäus, Gabor, 0D
McCarthy, Brian, 09
Mizeikis, Vygantas, 0T
Moroko, M., 0O
Müller, Michael, 0H
Na, Yongjin, 16
Naidoo, Darryl, 0O
Ngobeni, Chris, 0O
Nolte, Stefan, 0D
Ocylok, Sörn, 0C
Ostroverkhov, Victor, 09
Ploshikhin, V., 08
Pohl, M., 0V
Purlys, Vytautas, 03
Ramm, Roland, 0D
Ramokolo, R., 0O
Riede, Mirko, 0H
Riegel, H., 0G, 0V
Ruck, S., 0G, 0V
Sato, Yuji, 0M, 0Y, 0Z
Schab, Johannes C., 0H
Schanz, J., 0V
Schneider, G., 0G
Schubert, T., 0G
Schurr, J., 0G
Seidel, André, 0H
Set, Sze Yun, 0W
Seyfarth, Brian, 0D
Shi, Kebin, 16
Shibata, T., 0Z
Ślodycz, M., 08
Srisawadi, Sasitorn, 0M
Subbaraman, Harish, 0P
Tanprayoon, Dhriti, 0M
Tičkūnas, Titas, 03
Tsukamoto, Masahiro, 0M, 0Y, 0Z
Ullsperger, Tobias, 0D
Valentin, M., 0L
Yamashita, Shinji, 0W
Zhang, Chao, 0W
Zhu, Chen, 0Q

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- 1 New Technologies in DLW: Joint Session with 10909 and 10930
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Harald Giessen, Universität Stuttgart (Germany)
- 3 Powder-bed SLM Metal Printing
Henry Helvajian, The Aerospace Corporation (United States)
- 4 New Technology for Copper Printing
Hongqiang Chen, GE Global Research (United States)
- 5 Multi-Materials Printing
Henry Helvajian, The Aerospace Corporation (United States)
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Henry Peng, Institute of Applied Research on Intelligent Science & Technology (China)
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